



life.augmented

# A low power, high dynamic range SPAD for sustainable sensing

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International SPAD Sensor Workshop

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# Optical sensing solutions application domains



## Personal Electronics

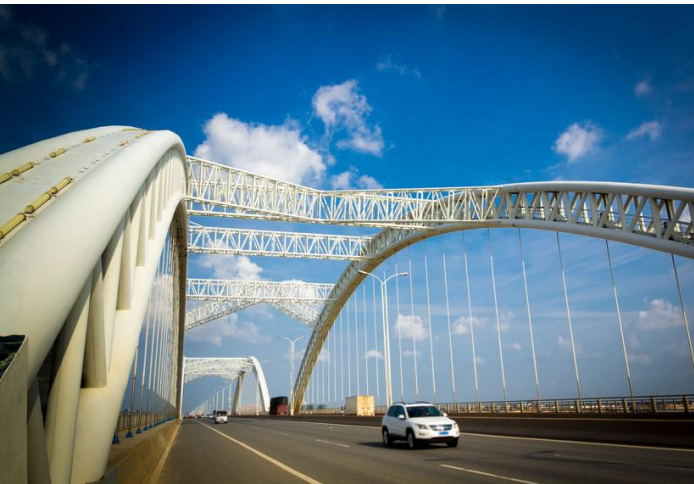
Camera assist

AR / VR

## Industrial & Robotics

Obstacle detection

Machine vision



## Automotive

In-cabin monitoring

LiDAR

## Computer & Peripherals

Presence detection

Security





# ST pioneer and leader in Time-of-Flight (ToF)

## ST is #1 Worldwide ToF sensor supplier

ToF Pixel Expertise  
SPAD/FPD

Advanced Photonics  
CMOS Process (40nm/3D)

Embedded ToF Processing & Depth ISP

Micro-Optics & Supply Chain

Illumination Expertise & Supply-chain

Advanced Packaging know-how & manufacturing

**4 Generations**  
of all-in-one ToF solution deployed in the past 5 years

**>170 phones with FlightSense™**  
Above 15 smartphone OEMs

**>Hundreds other customers**  
Hundreds non wireless end-products in the market

**>45,000**  
Evaluation kits deployed

**>1Bu**  
ToF units shipped. Mastering end-to-end supply chain

# Unlimited Applications



Lighting



Laptops



Tablets



Cleaning robots



Service Robots



Drones



Toys



ATM



Printers



Smart home



Industrial



Lockers



Vending machines



Projectors



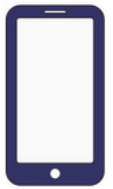
AR/VR



Faucets



Public Parking



Phones



Wearable & IoT



Dispensers



White Goods



Medical



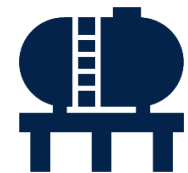
Farming



Logistics



Trucks



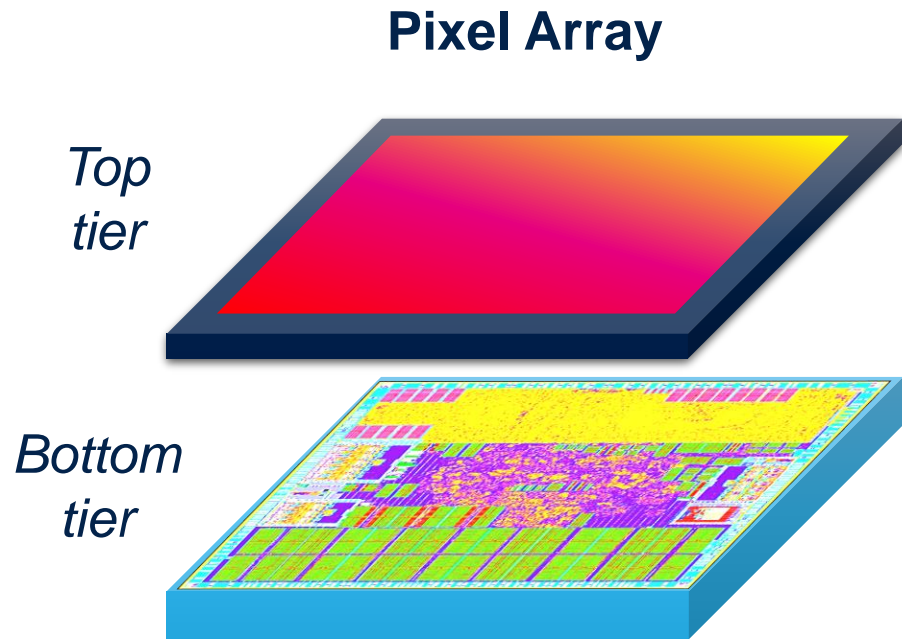
Tanks



Warehouse



# Wafer stacked CMOS image sensor



## Low power processing

Integrating both low noise analogue and high speed, low power, digital logic



## Pixel custom technology

- ▶ Optimised breakdown voltage
- ▶ Low DCR and high PDE in the near IR
- ▶ High dynamic range

## Innovative pixel-level top to bottom connection



## Advanced digital & analog CMOS

- ▶ High density & low power digital for efficient TDC
- ▶ Pixel-wide quench circuit implementation



# IMG140B-TOP technology | features

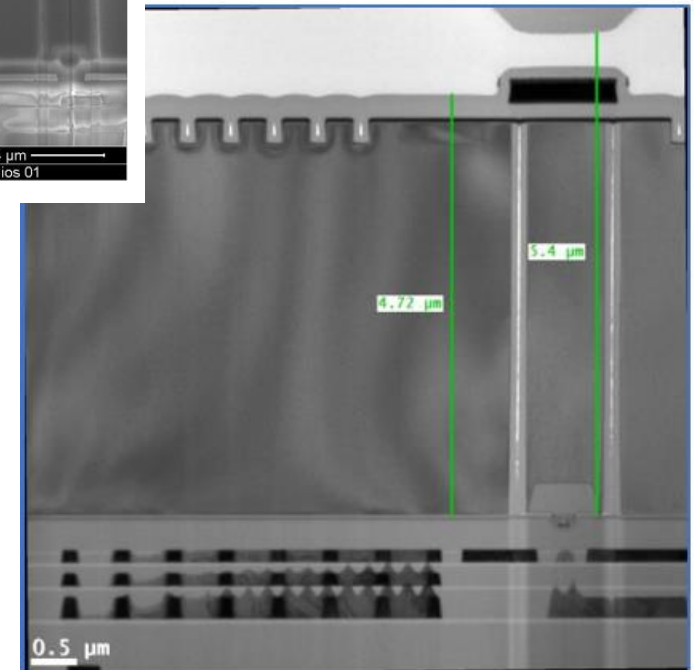
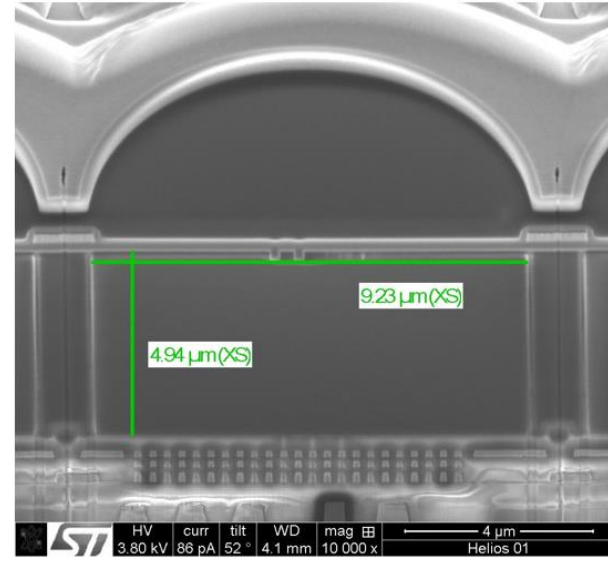
## FEATURES

### TOP tier process

- SPAD photodiode
- 4.5  $\mu\text{m}$  epitaxy for SPAD
- DTI for optical and electrical isolation
- Quench Resistor
- BSI Tungsten for shielding
- Microlens
- Structuration for QE enhancement

### BOTTOM tier process

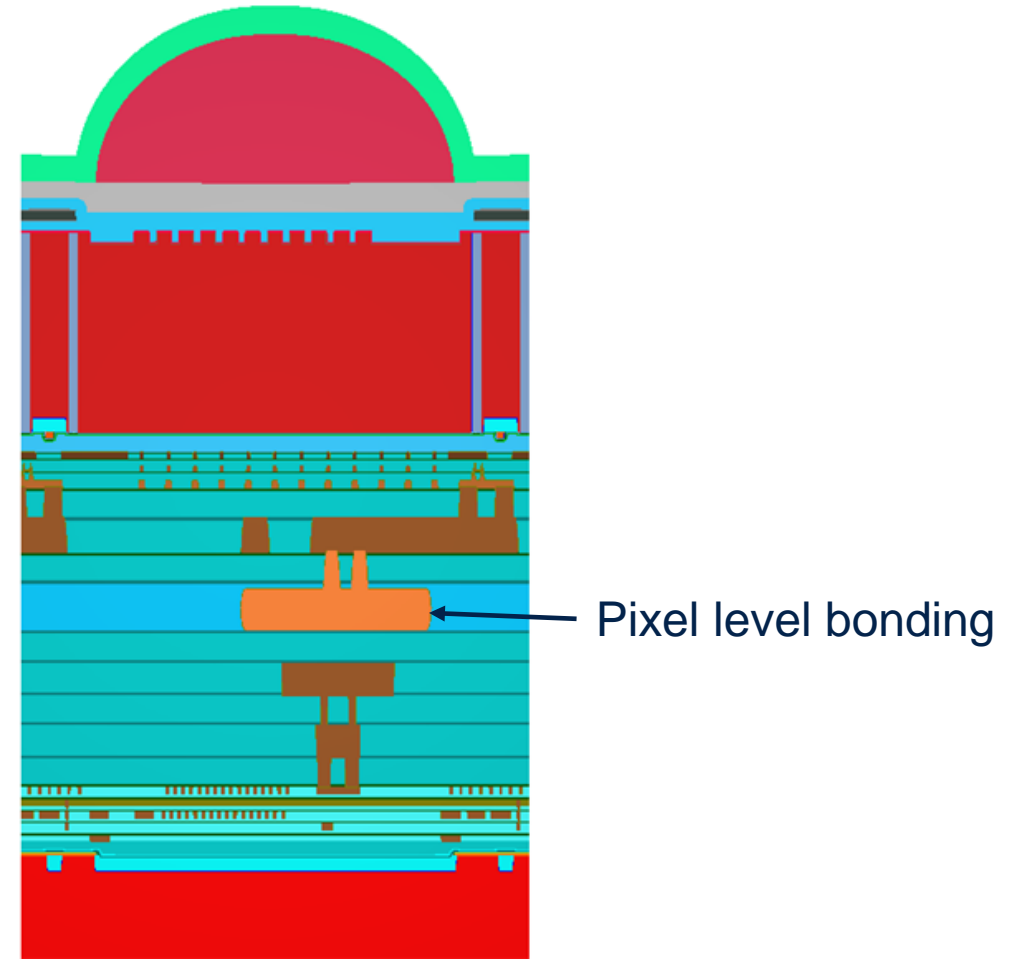
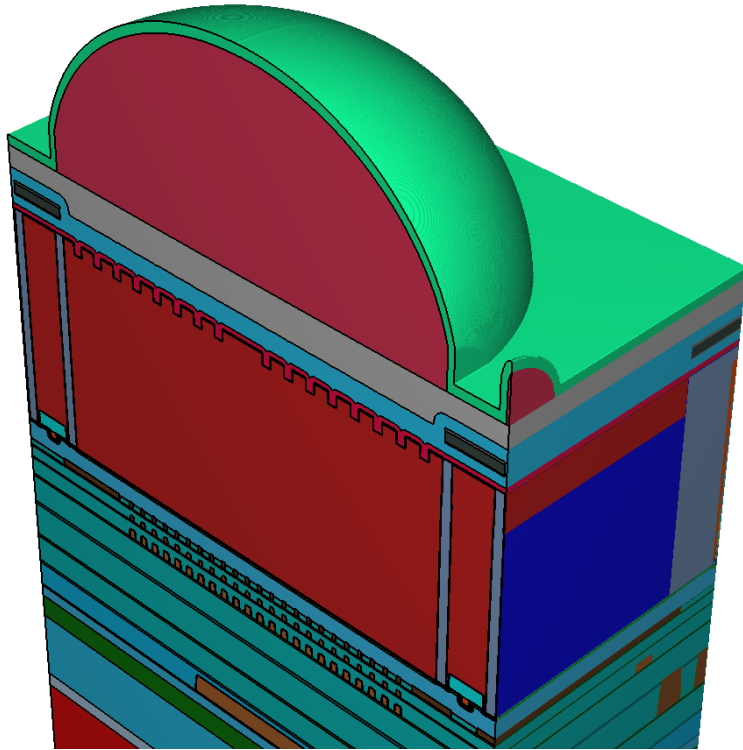
- 40nm CMOS
- Low power
- Dual gate oxide
- 7 metals levels
- Aligned with C40SPAD to allow IP reuse



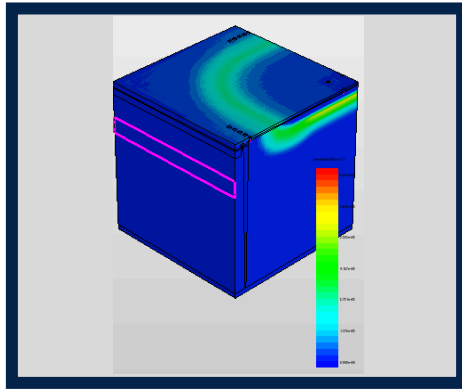
# The best of two worlds wafer stacked sensor

## SPAD dedicated technology

- Bottom tier quench circuit for high FF
- Large collecting volume to maximise PDE

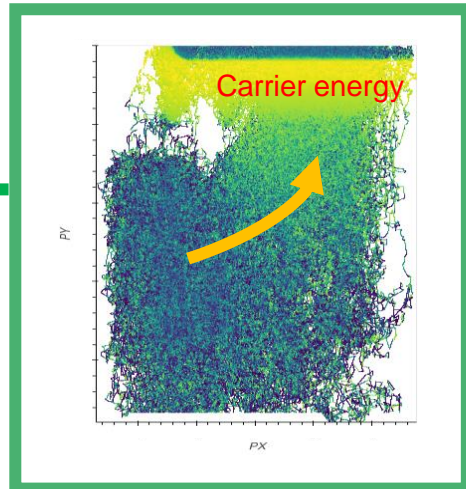
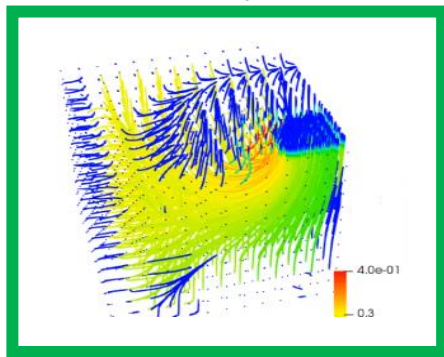


# TCAD: Process/ Device simulations



# Monte Carlo

## McIntyre

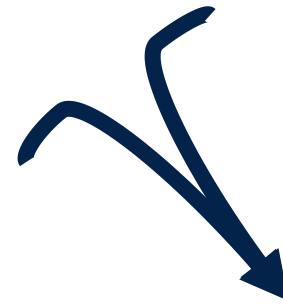
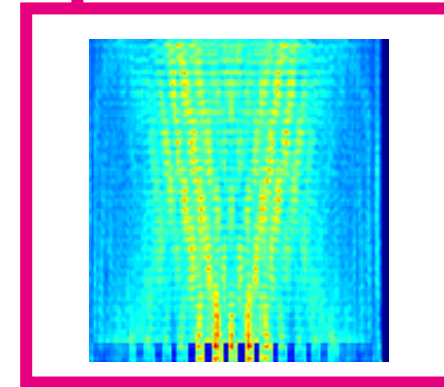


Breakdown Probability

# Electro-optical simulations

## Optical Absorption

- 3D Finite-Difference
- Time Domain simulations

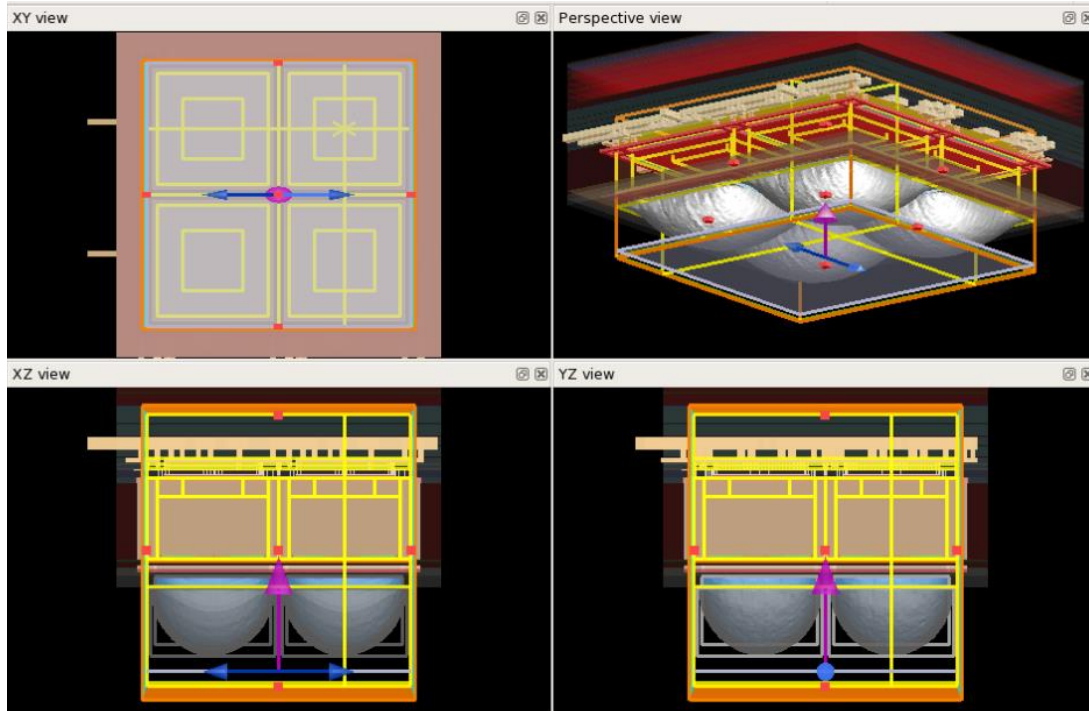


Photon detection probability



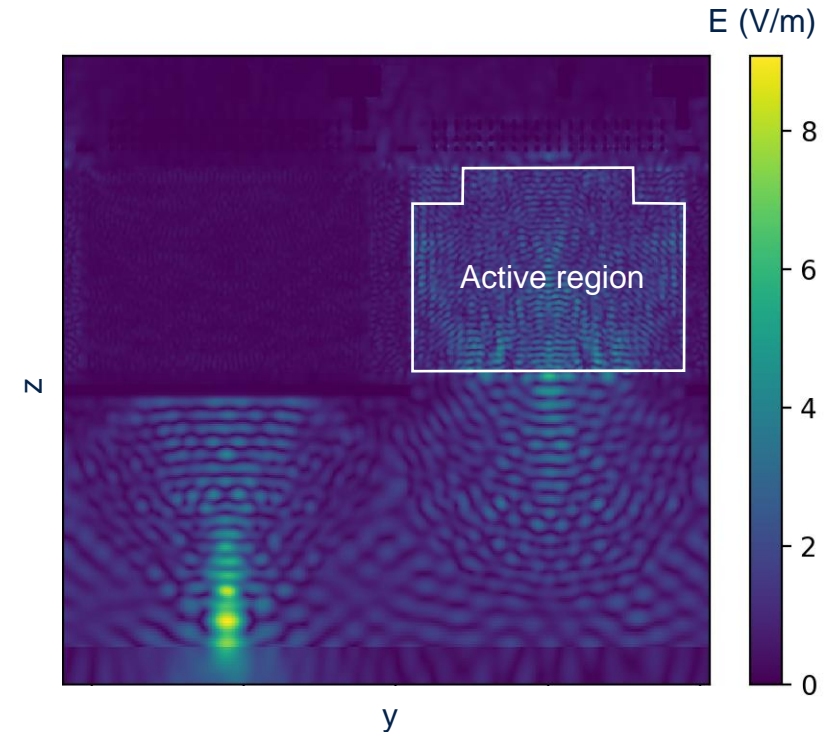
# Optical simulations: methodology

3D model of SPAD pixels:



Use 3D electromagnetic FDTD algorithm to solve Maxwell equations (Lumerical software)

Electromagnetic fields inside pixel

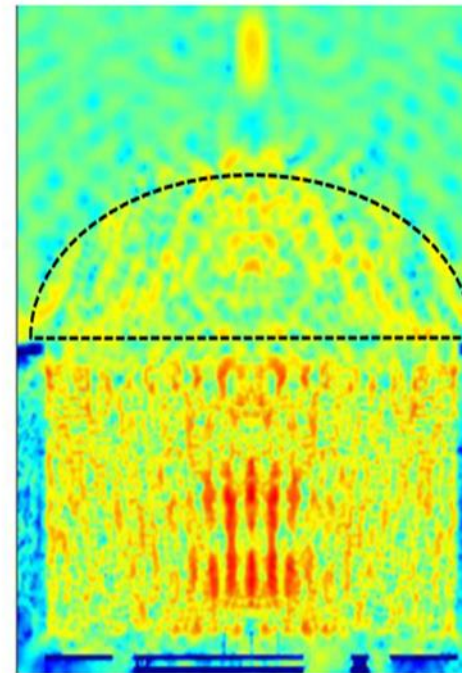
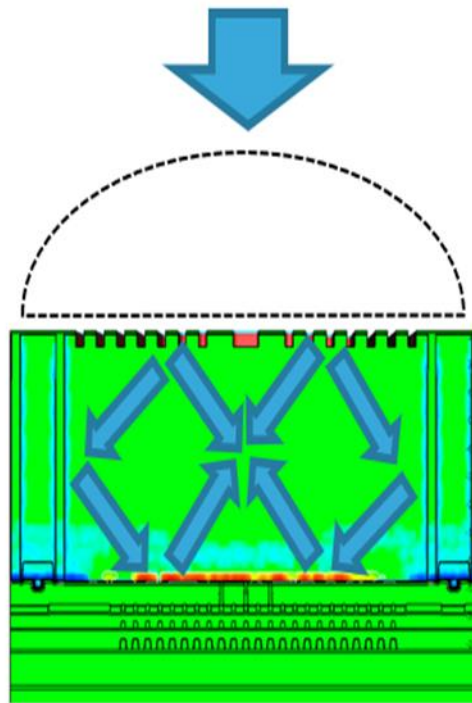


Extract optical absorption and crosstalk

# Structuration design and simulation

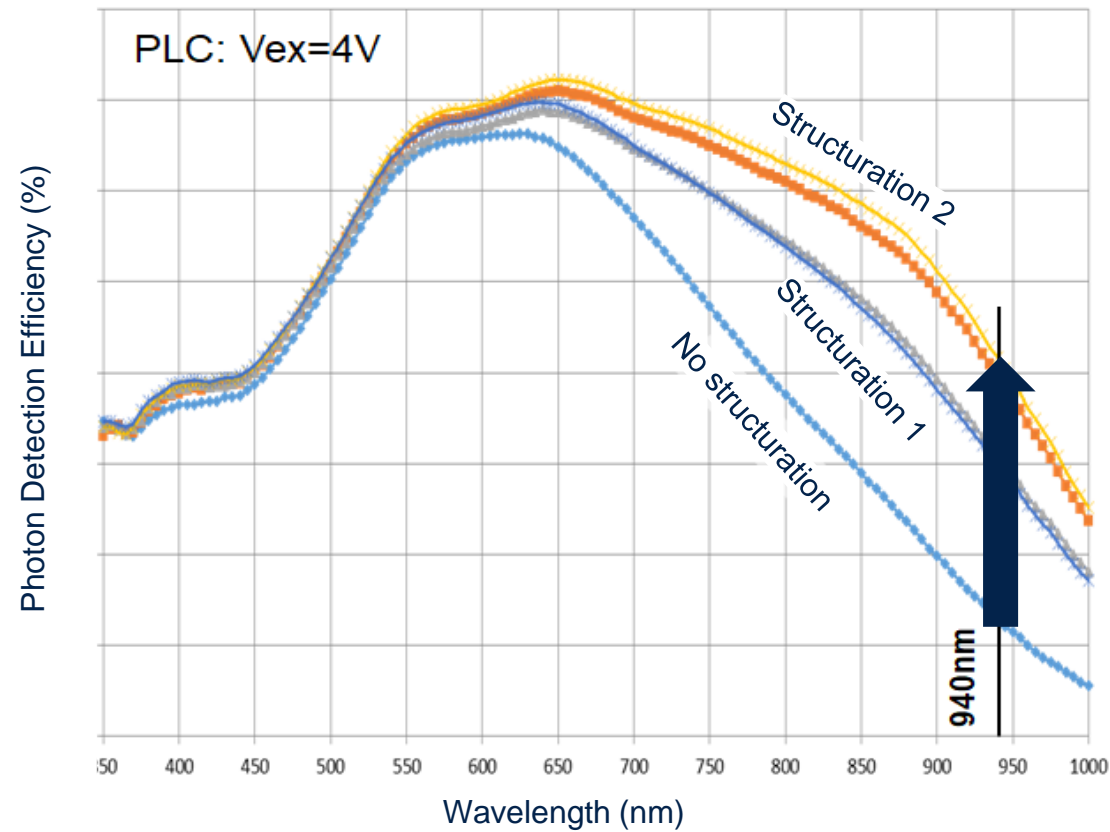
3D architecture with structuration: multiple reflections

→ path length  $\times N$  (with  $N \gg 2$ )



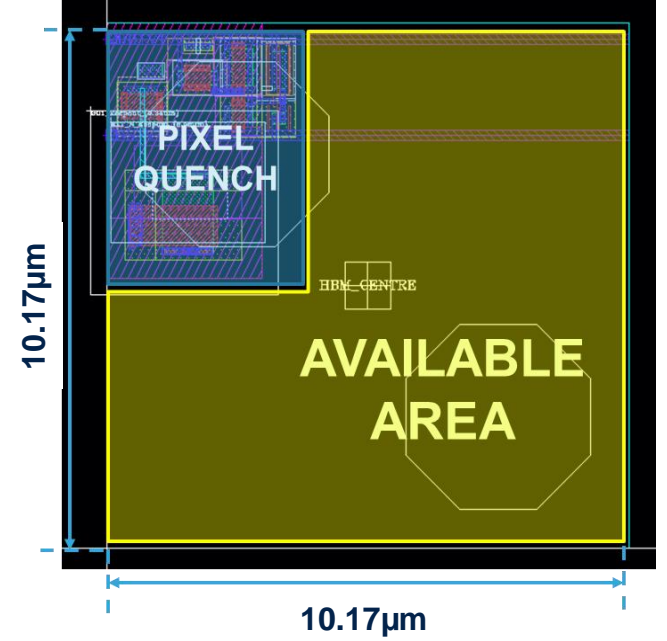
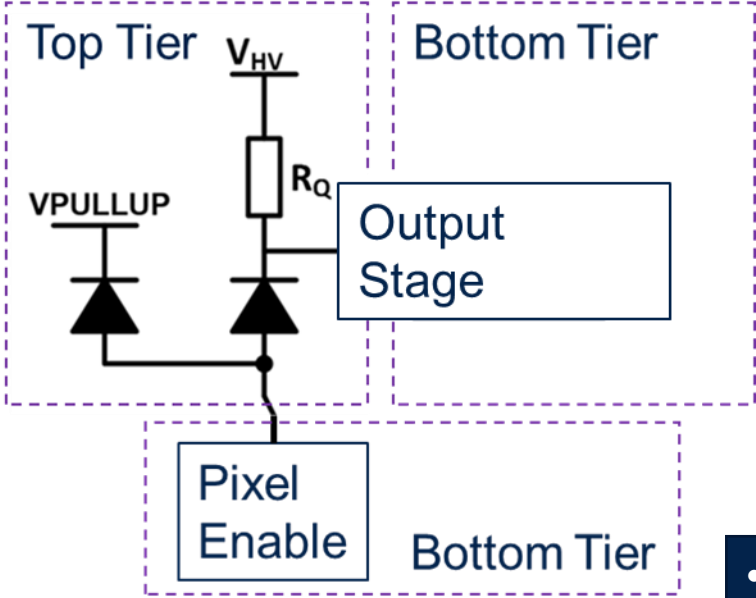
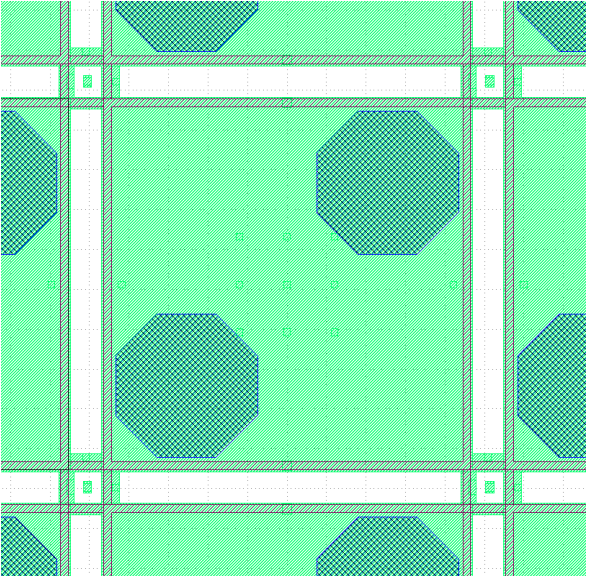
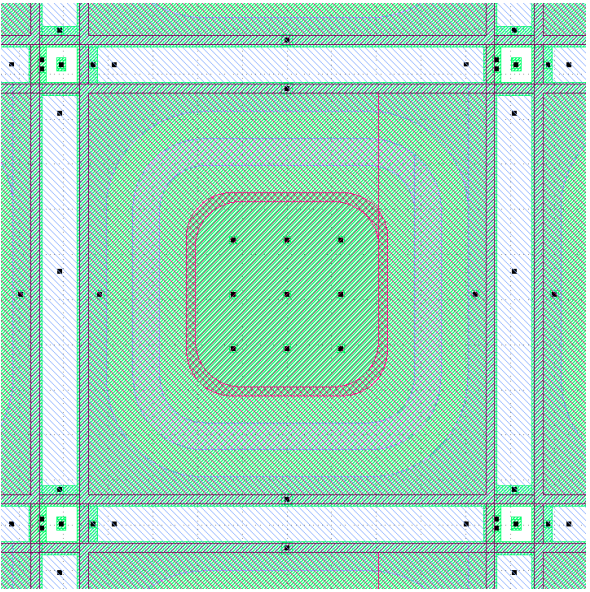
# Structuration impact

3D architecture with structuration: multiple reflections  
→ Photon detection efficiency improvement



~3x increase in PDE

# 3D40SPAD - Pixel



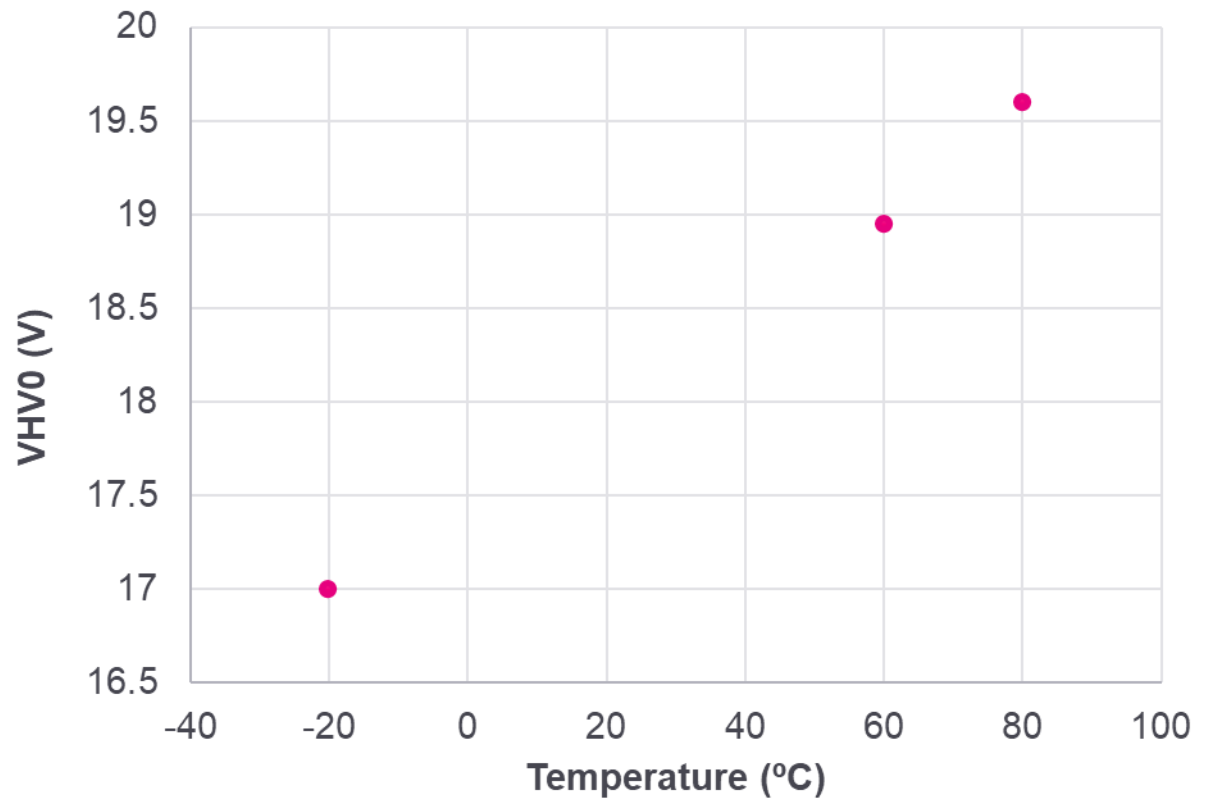
- Pixel quench circuit occupies <25% of available area in bottom tier
- GO1 compatible pixel output voltage
- Positive Vbd compatible with efficient on-chip charge pumping

# Breakdown Voltage vs Temperature

Diode junction engineered to minimise  $V_{bd}$  → minimal power consumption

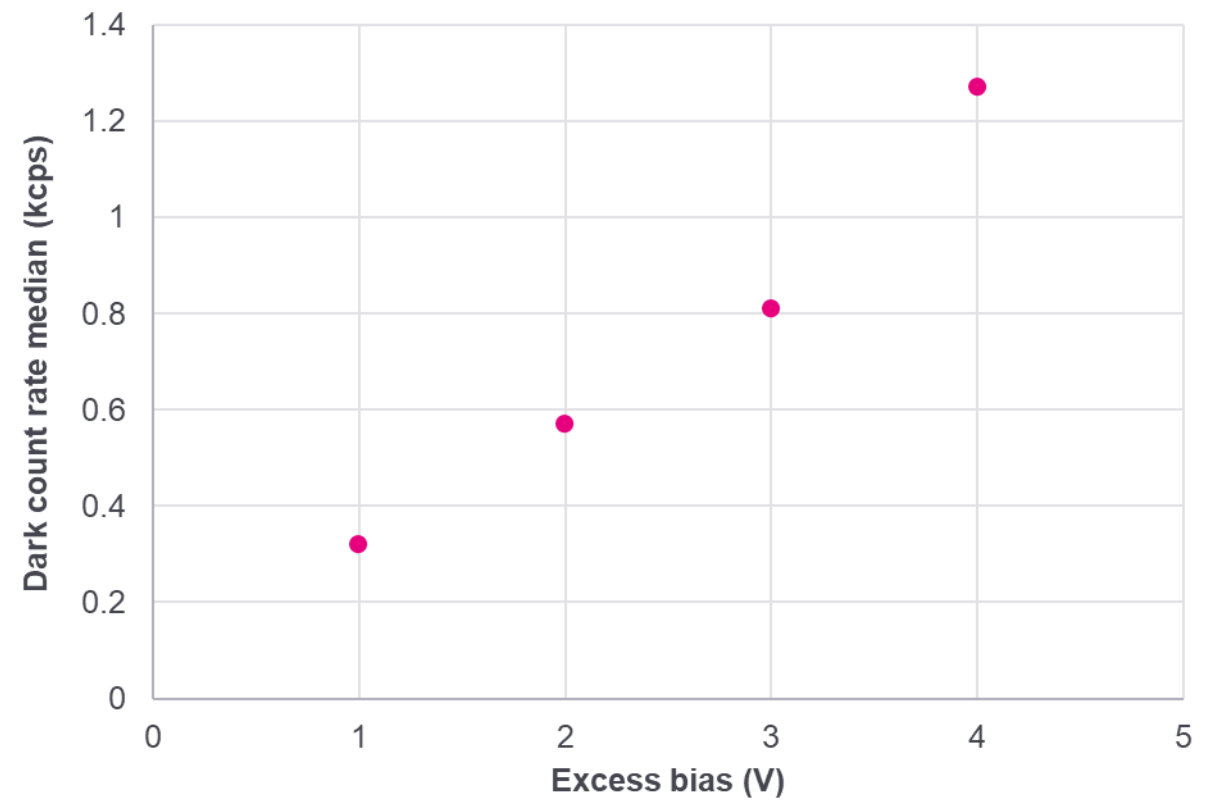
VHV0			
Temp [°C]	-20	60	80
VHV0 [V]	<b>17.0</b>	<b>18.9</b>	<b>19.6</b>

VHV0 is the minimum voltage for which the SPAD pixel produces an output  
 $VHV0 = V_{bd} + V_{out\_thresh}$

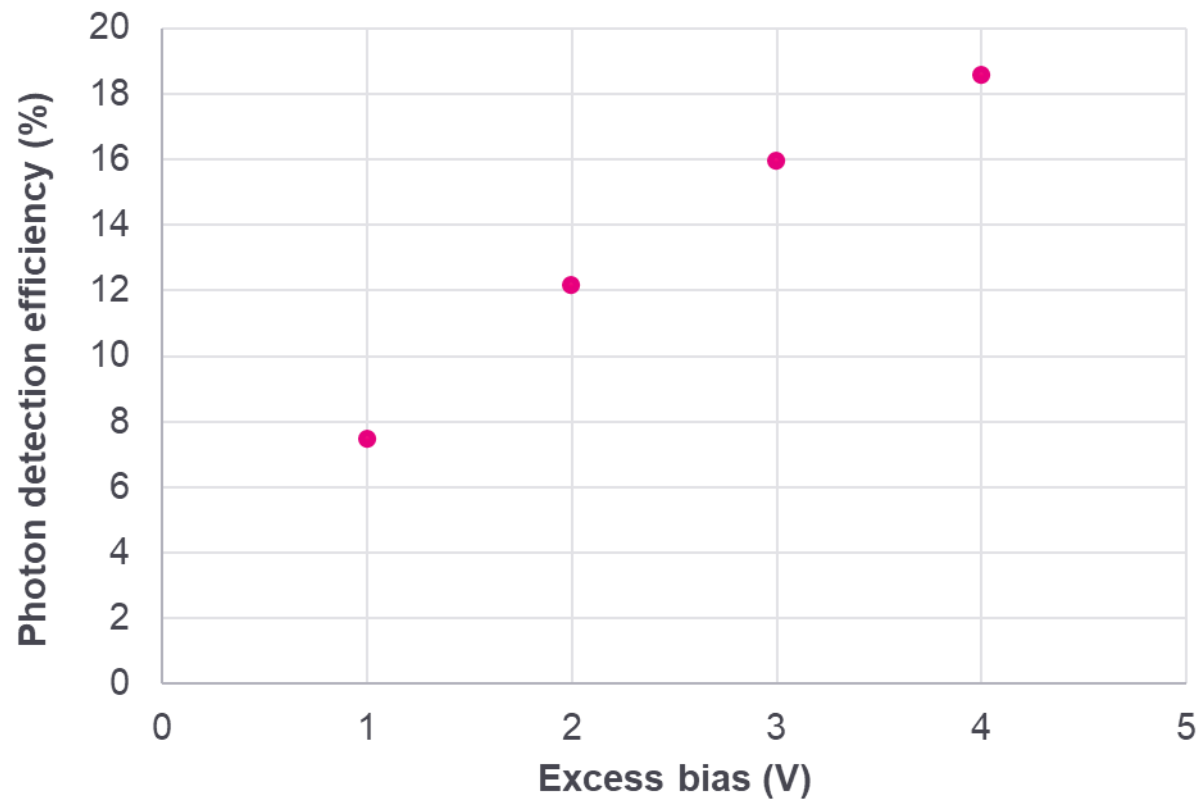


# Dark count rate @ 60°C

Dark count rate				
V <sub>excess</sub> [V]	1	2	3	4
DCR Med [kcps]	<b>0.32</b>	<b>0.57</b>	<b>0.81</b>	<b>1.27</b>



# Photon detection efficiency @ 60°C

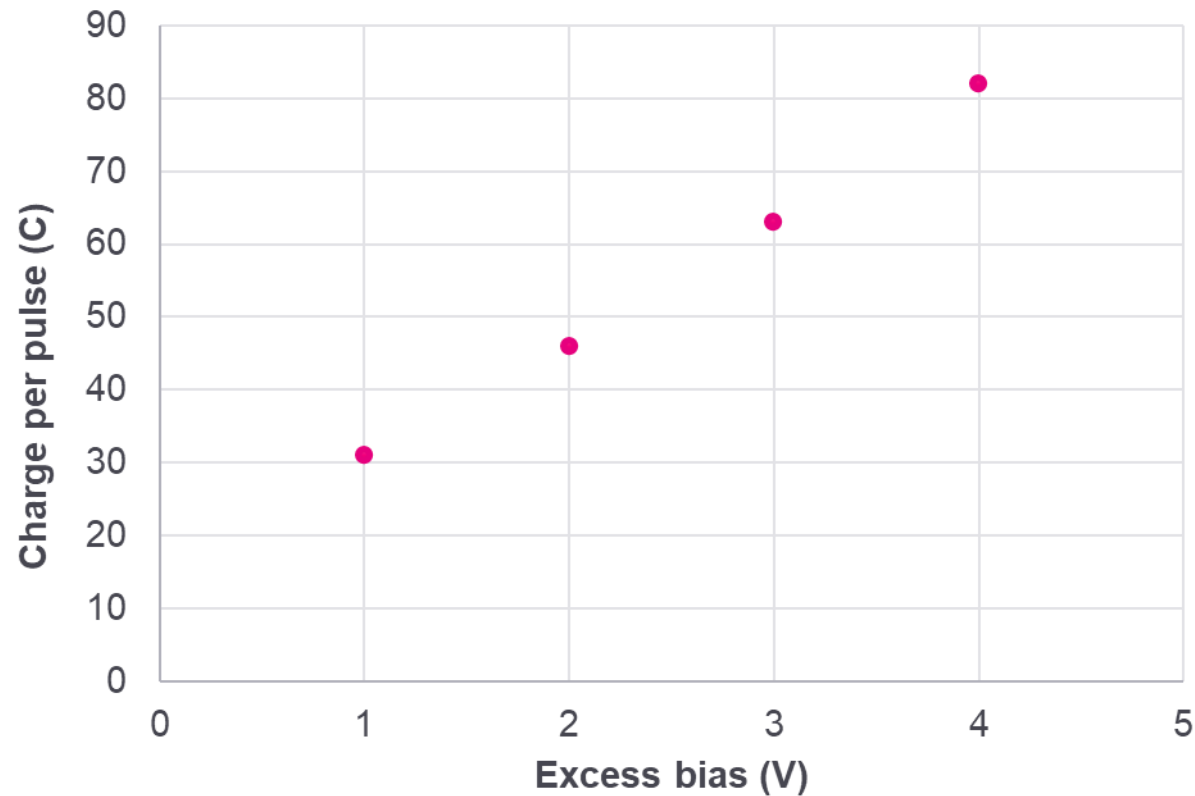


Photon Detection Efficiency				
V <sub>excess</sub> [V]	1	2	3	4
PDE Median [%]	7.5	12.1	15.9	18.6

# Charge per pulse vs $V$ excess (@ 60°C)

Low charge per pulse @ low VHV enables high resolution array and/or low array power consumption

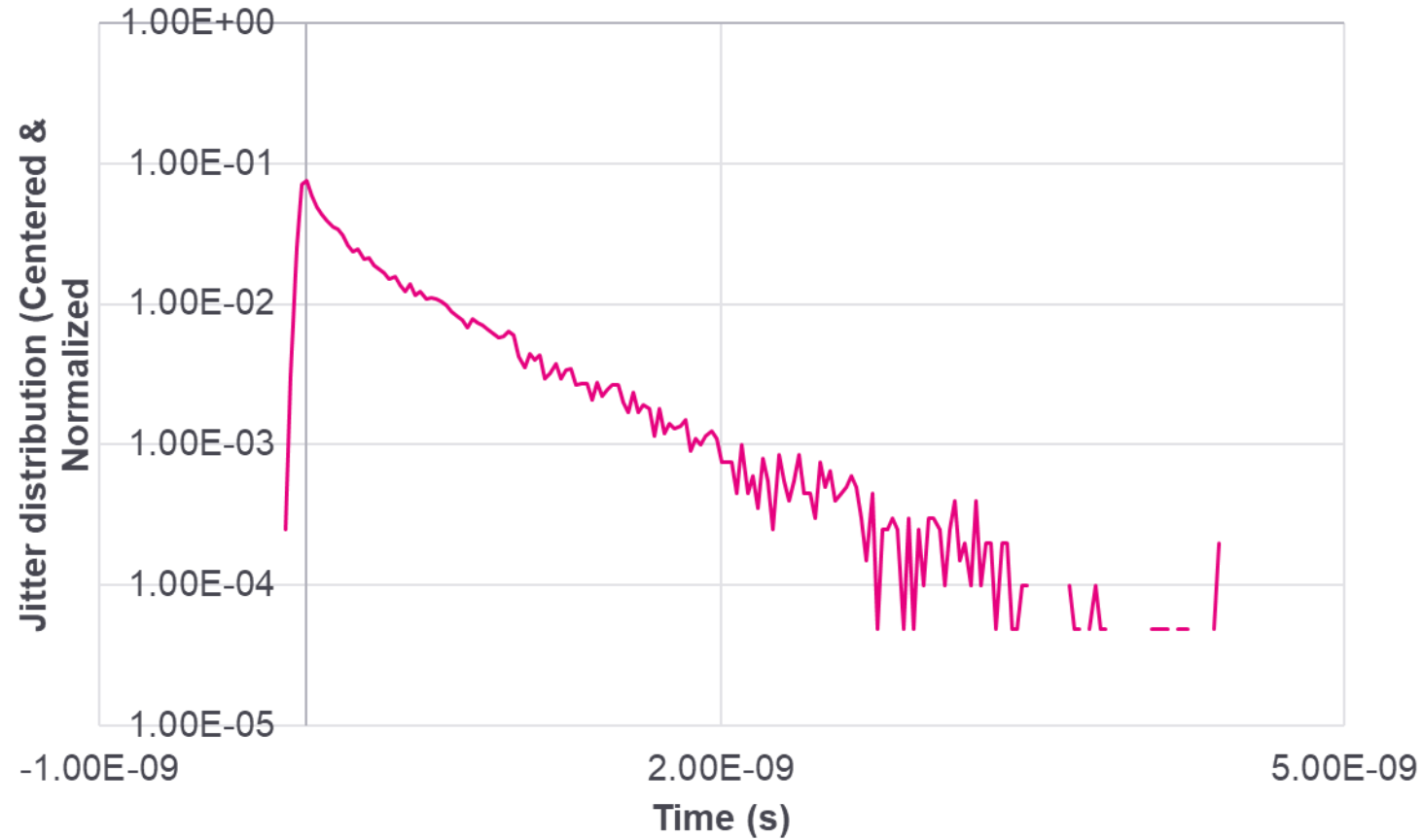
→ In-line with ST sustainability strategy



Charge per pulse				
Vexcess [V]	1	2	3	4
Charge per pulse [fC]	31	46	63	82



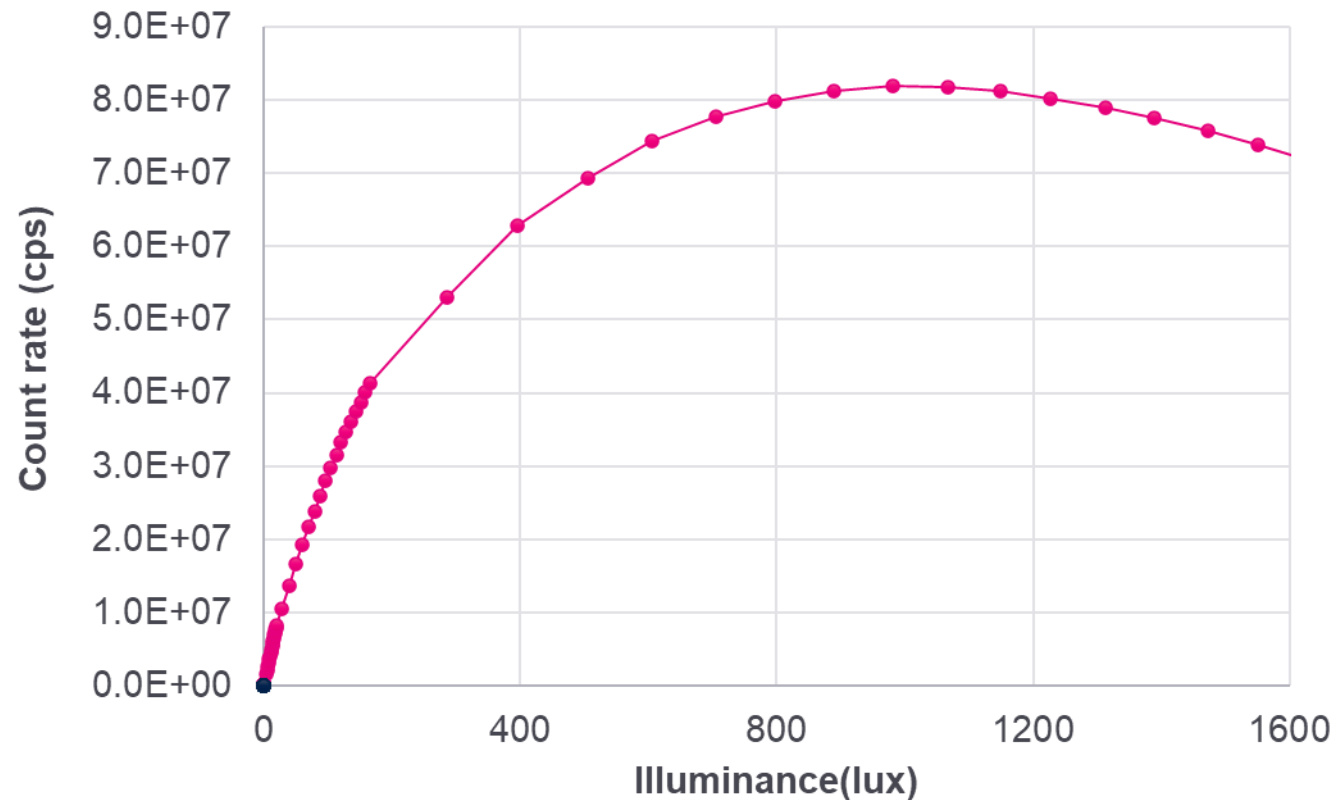
# Timing jitter @ 60°C



Timing Jitter	
Vexcess [V]	3
FWHM [ps]	<b>169</b>
Pop < 90% [ns]	<b>1.3</b>

# Dynamic range @ 60°C

High QE diode requires high dynamic range pixel → maximise system benefit



Dead Time / Max Count Rate	
Vexcess [V]	3
Max Count Rate [Mcps]	<b>82</b>
Dead Time – 1/MCR [ns]	<b>12.2</b>
Dead Time – 1/(e*MCR) [ns]	<b>4.5</b>

# Access to our advanced imaging technologies through foundry model

## ST Imaging manufacturing & engineering know-how



**Billions imaging devices shipped**  
**World-class 12" wafer fabs**  
**Recognized expertise across Imaging value chain & ecosystem**

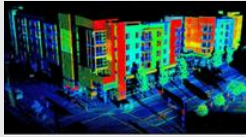
## Premium services beyond traditional foundries



**Access to differentiating technologies**  
**Reliable partner, flexible business model**  
**Benefit from broad imaging IP portfolio and expertise**

# Where to find us

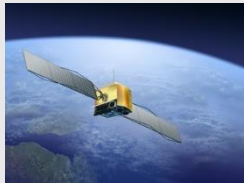
LiDAR



ROIC & Thermal IR



Space & Defence



Machine Vision



Cinematography



DSLR



X-Ray



Medical



# We are creators and makers of technology



One of the world's largest semiconductor companies



**48,000** employees of which  
**8,400** in R&D



**\$12.8 B** revenues  
in 2021



Over **80** sales & marketing  
offices serving over **200,000**  
customers across the globe



**13** manufacturing sites

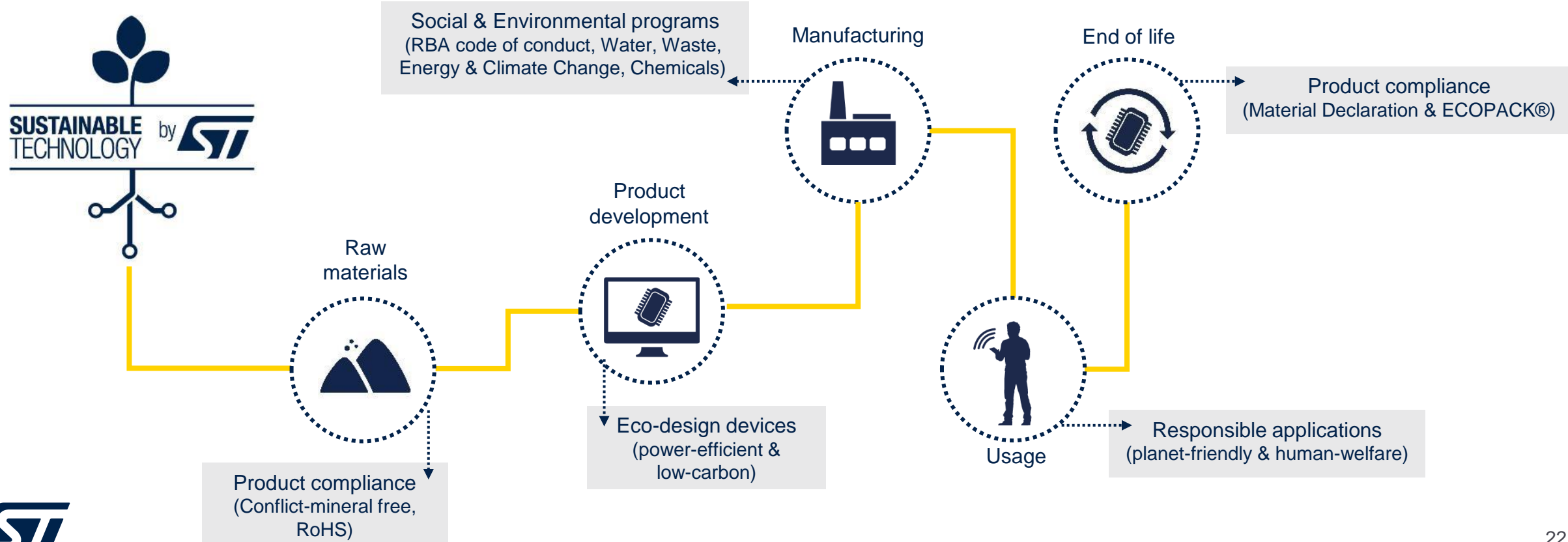


Signatory of the United Nations Global Compact (UNGC)  
Member of the Responsible Business Alliance (RBA)

# Sustainable technology

Our Sustainable Technology program aims to develop responsible products which:

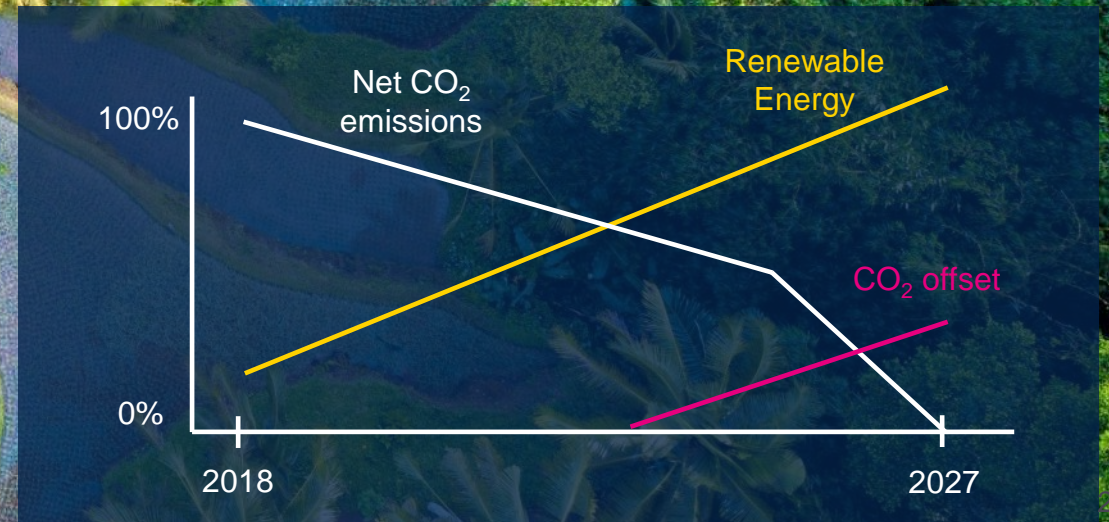
- improve our social and environmental footprint at every stage of the product life
- have the greatest positive impact on the planet and people in the end-application



# We will be carbon neutral by our 40<sup>th</sup> anniversary

## Milestones

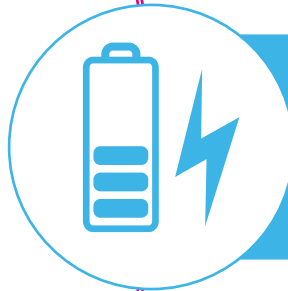
- Compliance with the 1.5°C scenario by 2025 – recognized by SBTi
- Carbon neutral by 2027
- Sourcing 100% renewable energy by 2027
- Collaborative programs and partnerships for carbon neutrality throughout our ecosystems



# Take aways



Optimised diode breakdown voltage



Low charge per pulse



High dynamic range taking full advantage of high PDE diode



# Acknowledgements

Imaging Division team in Edinburgh (UK) and Technology R&D team in Crolles (France) at STMicroelectronics

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**Thank you!**